



AZ® 50XT Photoresist

Thick Positive Novolak Photoresist For Plating & Etch Applications

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AZ® 50XT Photoresist

- Positive resist for developing plating and wafer bumping applications
- 50 to 80 micron single coat capability. Up to 120µm FT double coat capability
- 3 to 1 aspect ratio. Excellent sidewall profiles. Wide process latitude
- Inorganic developer recommended
- Compatible with existing thick film processes



Copper studs AZ[®] 50XT at 75µm Film Thickness



Solder studs (SnPb) AZ[®] 50XT at 75µm Film Thickness



AZ® 50XT Spectral Response Curve



AZ Electronic Materials

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AZ[®] 50XT on Copper Expose on Ultratech-Saturn, 75µm FT, 100µm CH,



2400 mJ



2600 mJ

2700 mJ

2800 mJ



2900 mJ

3000 mJ

3100 mJ

3200 mJ

3300 mJ



AZ[®] 50XT on Cu – Plating Performance Expose on Ultratech-Saturn, 75µm FT, 100µm CH,



2400 mJ

2500 mJ

2600 mJ

2700 mJ

2800 mJ



Post Copper Plating and Strip



AZ[®] 50XT Photoresist Exposure Latitude on Si, 20µm Contact Holes, FT = 25µm



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Z Electronic Materials

AZ[®] 50XT Photoresist Copper Plating - ~20µm High Bumps



CD = 20µm

CD = 30µm

CD = 50µm





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